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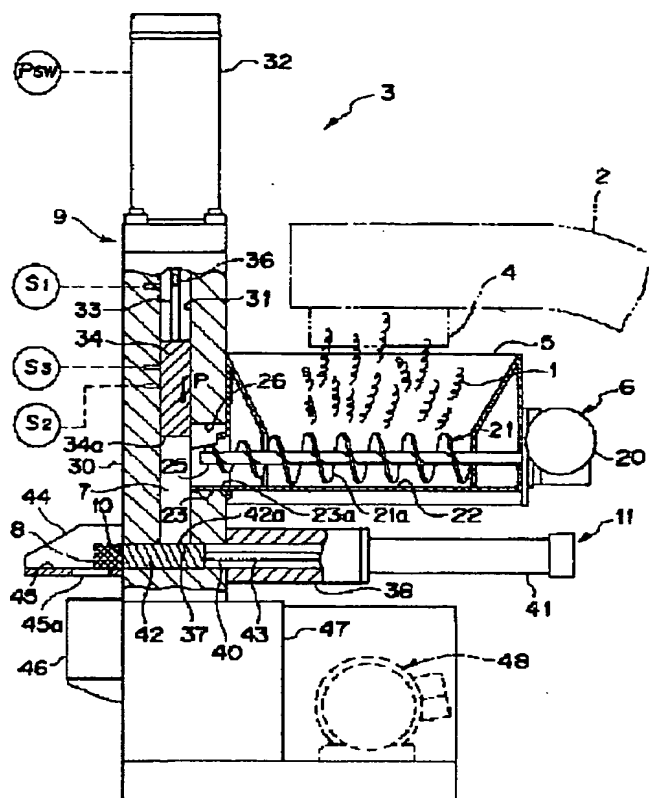
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TITLE : CUT CHIP PROCESSING DEVICE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a cut chip processing device which can compress a cut chip by a large molding surface pressure while a device total unit is formed into compactness.

SOLUTION: A device comprises a hopper 5 for feeding a cut chip 1 generated at the time of cutting work, screw device 6 provided in a lower part of this hopper to convey a cut chip therein to outside the hopper, cut chip compressing means 9 receiving the cut chip 1 conveyed by the screw device in a cylindrical compressing chamber 7 compressed and molded into a cut chip block 8 and a cut chip block discharge means 11 discharging the cut chip block. Outer diametric dimension of a screw 21, provided in the screw device to be driven and rotated, is formed in a large diameter in the inside of the hopper, and made in a tapered shape corresponding to sectional dimension of the compression chamber becoming smaller toward the compression chamber from the hopper. Inner dimension of a cut chip guide part 23, at least surrounding a lower part of the screw between the hopper and the compressing chamber to guide a cut chip to the compressing chamber, is made in a tapered shape to be matched with a shape of the screw.

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